

Parameter	Symbol	Rating	Units	
Load Voltage	VL	40	V	
Load Current	IL	2.5	Α	
On-Resistance	Ron	0.06	Ω	
On-Resistance	V/io	1500	Vrms	



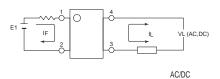


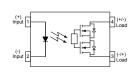
(Unit: mm)





E534710





- 1. LED Anode
- 2. LED Cathode
- 3.4. Drain(MOS FET)



### **APSEMI PhotoRelays**

APSEMI Photorelays are the most reliable, technically advanced logic-to-power interface devices. Their basic function is to take a low current signal from a microprocessor to control the switching of both AC and DC loads, while providing an isolation barrier between logic and power. While this function is common to all relays, Photorelays provide distinct advantages over their mechanical counterparts including:

- Long life (No limit on mechanical and electrical
- lifetime)Bounce-free switching
- Higher speed and high frequency switching
- Higher sensitivity (less power consumption)
- Immunity to EMI or RFI

- No have voltaic arc, bounce, and noise More
- · resistant to vibration and impact AC or DC load
- switching
- Small package size

#### **Function**

APSEMI PhotoRelays operate by taking a low level input current (<5mA) that energizes an input Infrared LED, which is optically-coupled to a Photo-diode array chip. This IC in turn generates a photo voltage that powers two MOSFETs typically connected in a source-to-source con¦ guration, allowing for both AC and DC output loads. Photorelay basically move photons to accomplish their switching function, they incur no mechanical wear and tear, providing consistent reliable switching.

## **Applications**

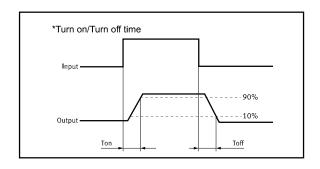
These advantages make APSEI Photorelays the ideal choice for:

- Telecom/Datacom switching
- Multiplexers
- Meter reading systems
- Data acquisition
- Medical equipment
- Battery monitoring
- I/O Sub-Systems

- Robotics
- Aerospace
- Home/Safety security systems
- Process Control
- Energy Management
- Reed Relay EMR Replacement
- Programmable Controllers

#### **TPYES**

Cotogoni	Output Rating		Doolsono	Part No.	Doolsing Overtity	
Category	Load Voltage	Load Current	Package	Part No.	Packing Quantity	
AC/DC	40V	2.5A	SOP-4	APY211G2S	2000pcs /reel	





# Absolute Maximum Ratings (Ta = 25°C)

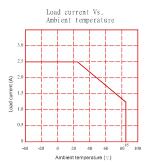
Item		Symbol	Value	Units	Note	
	Continuous LED Current	lF	50	mA		
Input	Peak LED Current	<b>I</b> FP	1000	mA	f=100Hz, duty=1%	
	LED Reverse Voltage	VR	5	V		
	Input Power Dissipation	Pın	75	mW		
	Load Voltage	V∟	40	V(AC peak or DC)		
	Load Current	l.	2.5	Α		
Output	Peak Load Current	Peak	5.0	Α	100ms(1 pulse)	
	Output Power Dissipation	Pout	400	mW		
Total Power	Dissipation	Р⊤	500	mW		
I/O Breakdov	vn Vo <b>l</b> tage	V <sub>I/O</sub>	1500	Vrms	RH=60%, 1min	
Operating Temperature		Topr	-40 to 85	℃		
Storage Temperature		T <sub>stg</sub>	-40 to 100	℃		
Pin Soldering Temperature		Tsol	260	°C	10 sec max.	

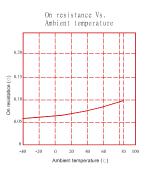
# Electrical Characteristics (Ta = 25°C)

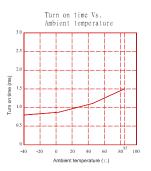
Item		Symbol	MIN.	TYP.	MAX.	Units	Conditions	
	LED Forward Voltage	VF		1.2	1.4	٧	I⊧=10mA	
	Operation LED Current	Fon		0.5	2.0	mA		
Input	Recovery LED Current	Foff		0.35	0.5	mA		
	Recovery LED Voltage	V <sub>Foff</sub>	0.7			٧		
							I⊧=5mA,I∟=100mA,	
	On-Resistance	Ron		0.06	0.1	Ω	Time to flow is within 1 sec.	
Output								
	Off-State Leakage	Leak			1.0	uA	V <sub>-</sub> =Rating	
	Current	Leak					VE-Itating	
	Output Capacitance	Cout		150		pF	V∟=0, f=1MHz	
Transmis	Turn-On Time	Ton		0.8	1.5	ms	I⊧=5mA, I∟=100mA,	
sion	Turn-Off Time	Toff		0.02	0.5	ms		
Counted	I/O Isolation Resistance	R <sub>I/O</sub>	10 <sup>10</sup>			Ω	DC500V	
Coupled	I/O Capacitance	Cı/o		0.8	1.5	pF	f=1MHz	

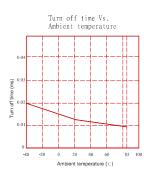


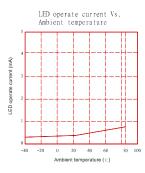
## **Engineering Data**

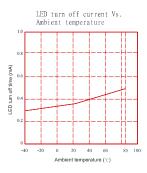


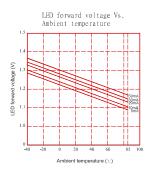


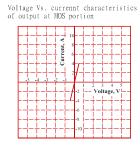


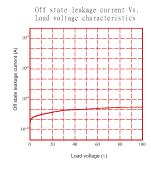


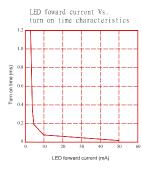


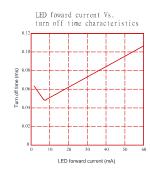


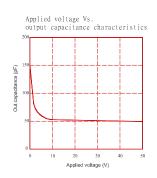












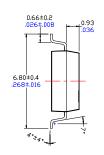


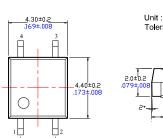
# **Dimensions and Package**

WW=WEEK

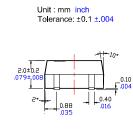
# 

Marking





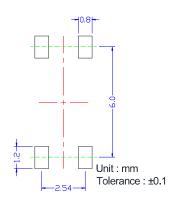
Surface mount terminal type



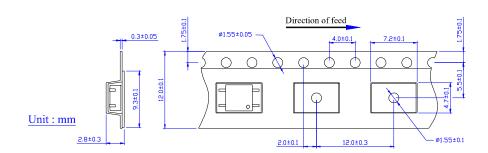
Lable



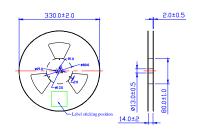
Recommended mounting pad (Top view)

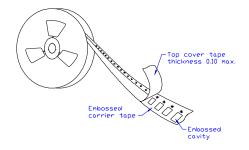


#### Tape dimensions





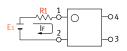


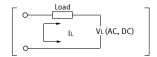




## **Using Methods**

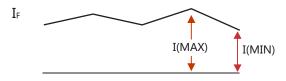
Examples of resistance value to control LED forward current (IF=5mA)





E1	R1 (Approx)
3.3V	300 Ω
5.0V	600 Ω
12V	1.9KΩ
24V	4.1K Ω

LED forward current must be more than 5mA , at I(MIN) ,and less than 30mA , at I(MAX).



### **Recommended Operating Conditions**

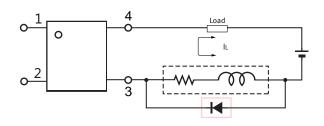
Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value):

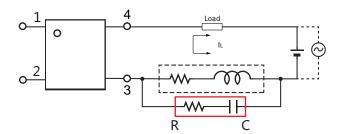
Characteristic	Symbol	Min	Тур.	Max	Unit
Forward current	lF	5.0	7.0	30	mA

#### **Protection Circuit**

Clamp diode is connected in parallel with the load. Absorb capacity with external diode.

CR Snubber is connected in parallel with the load. Absorb capacity with buffer capacity.





When adding diodes, buffer circuits (C-R), and other protections, they need to be installed near the MOS RELAY to be effective. Adding protection elements may result in a slow reset time, so adjust them according to the actual situation before use.

Note: When developing designs using this product, perform the expected performance of the equipment under the operating conditions recommended by the guidelines in this document. Continuous use under heavy loads (including, but not limited to, the application of high temperatures/current/voltage and significant changes in temperature, etc.) may result in deterioration of the reliability of this product.



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